

BSS84

50V P-Channel MOSFET

-0.13A -50V; $R_{DS(ON)typ}=1.9\Omega@-5V$, $R_{DS(ON)typ}=1.7\Omega@-10V$,

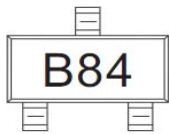
FEATURE

- Trench Technology MOSFET
- Low Gate Charge

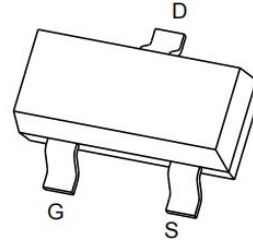
Application

- Load Switch for Portable Devices
- DC/DC Converter

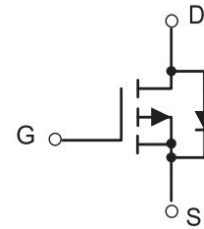
MARKING:



SOT-23



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-50	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ ($T_A = 25^\circ\text{C}$)	I_D	-0.13	A
Pulsed Drain Current ²	I_{DM}	-1.2	A
Power Dissipation ⁴ ($T_A = 25^\circ\text{C}$)	P_D	300	mW
Thermal Resistance from Junction to Ambient ⁵	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

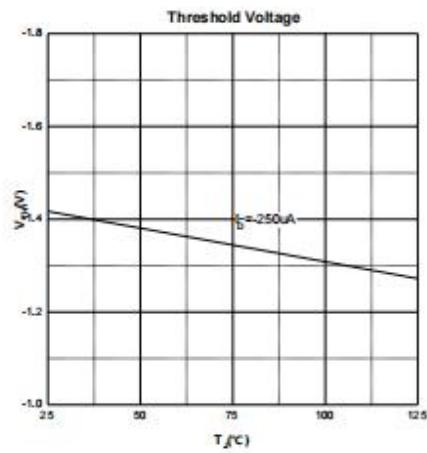
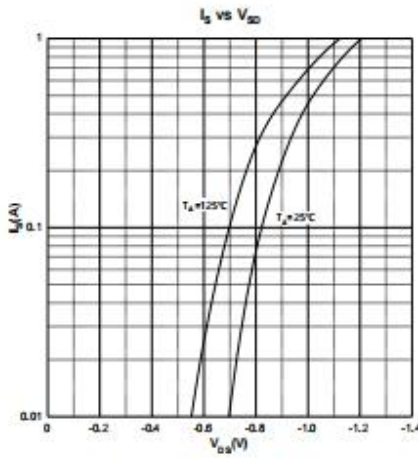
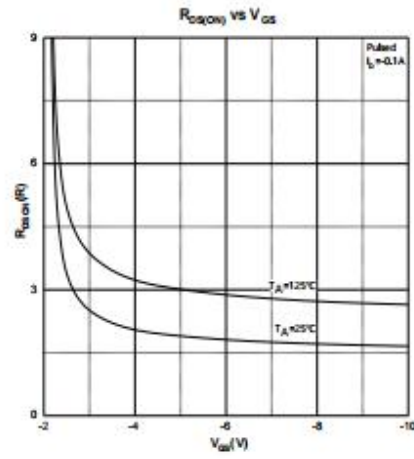
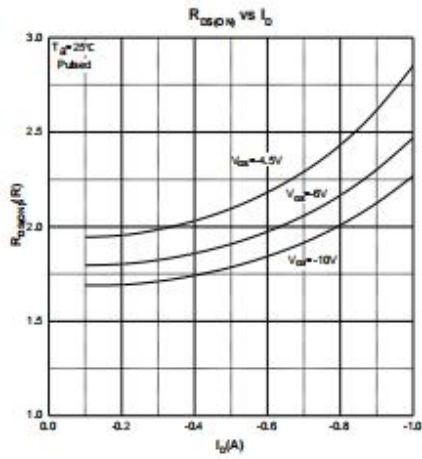
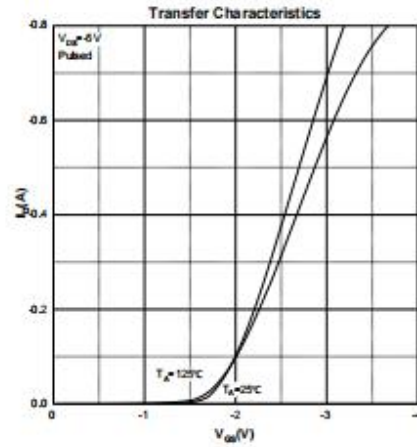
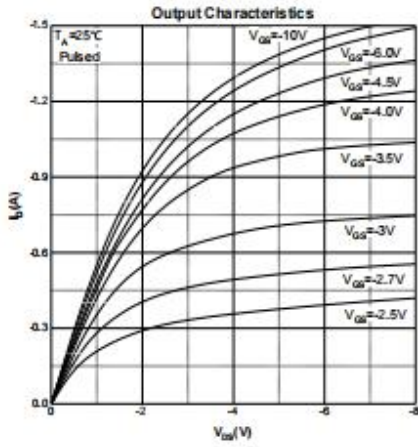
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

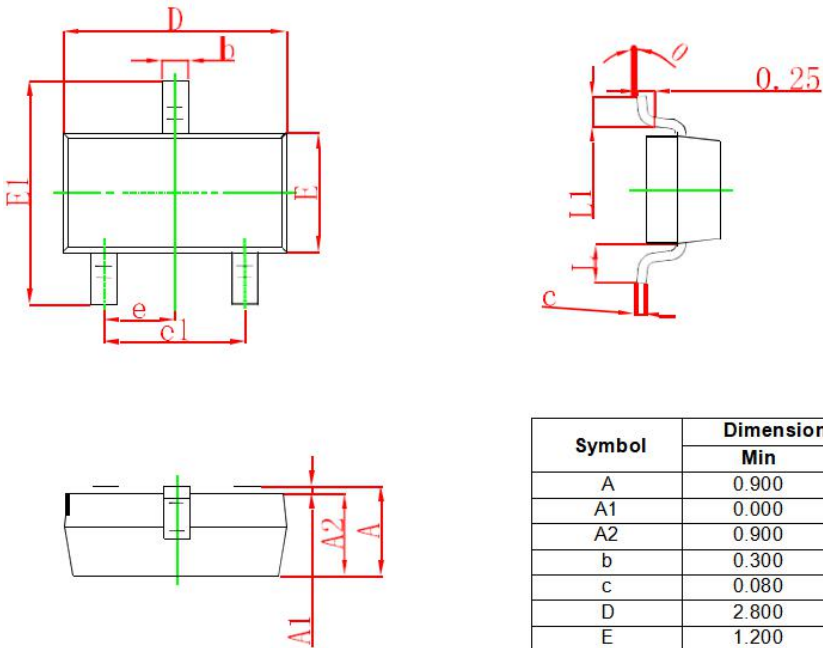
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
OFF CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-50			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -50V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
ON CHARACTERISTICS³						
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.9	-1.4	-2.0	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -0.1A		1.7	5	Ω
		V _{GS} = -4.5V, I _D = -0.1A		1.9	6	
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	V _{DS} = -25V, V _{GS} = 0V, f = 1MHz		32.9		pF
Output Capacitance	C _{oss}			5.48		
Reverse Transfer Capacitance	C _{rss}			3.31		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		73		Ω
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q _g	V _{DS} = -10V, V _{GS} = -10V, I _D = -0.1A		0.62		nC
Gate-Source Charge	Q _{gs}			0.13		
Gate-Drain Charge	Q _{gd}			0.11		
Turn-on delay time	t _{d(on)}	V _{DD} = -30V, V _{GS} = -10V, R _L = 110Ω, R _G = 50Ω		11		nS
Turn-on rise time	t _r			6		
Turn-off delay time	t _{d(off)}			19		
Turn-off fall time	t _f			8		
SOURCE-DRAIN DIODE CHARACTERISTICS						
Diode Forward voltage ³	V _{SD}	V _{GS} = 0V, I _S = -0.1A			-1.2	V

Notes :

1. The maximum current rating is limited by Chip.
2. Pulse Test : Pulse Width ≤ 10 μs, duty cycle ≤ 1%.
3. Pulse Test : Pulse Width ≤ 300 μs, duty cycle ≤ 2%.
4. The power dissipation PD is limited by T_J(MAX) = 150° C.
5. Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A = 25° C.

Typical Electrical and Thermal Characteristics





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°